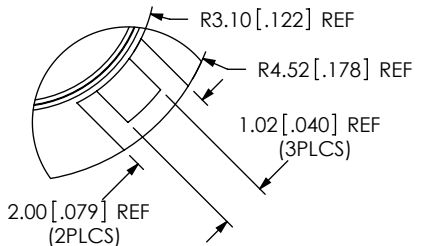
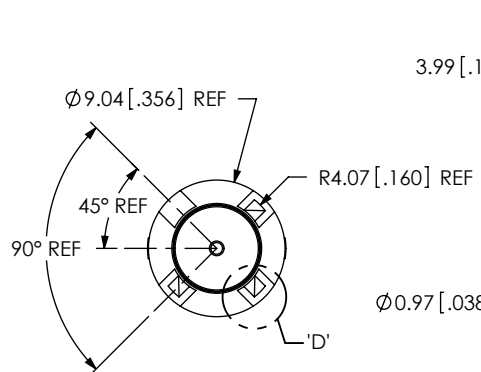
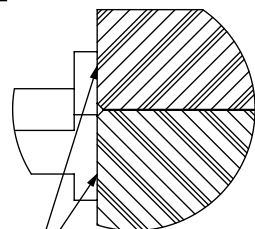


DO NOT SCALE FROM THIS PRINT

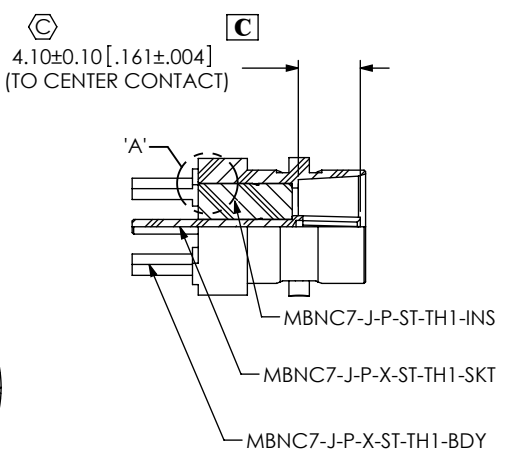
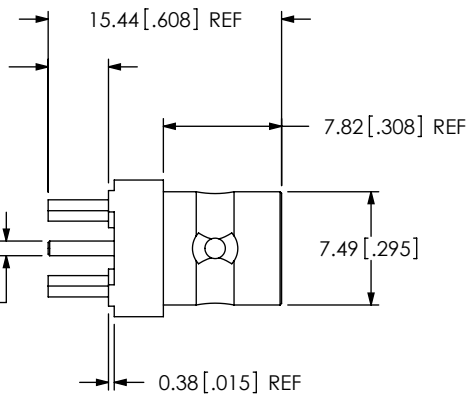
DESIGNED & DIMENSIONED IN MILLIMETERS [INCHES]



DETAIL 'D' SCALE 6:1



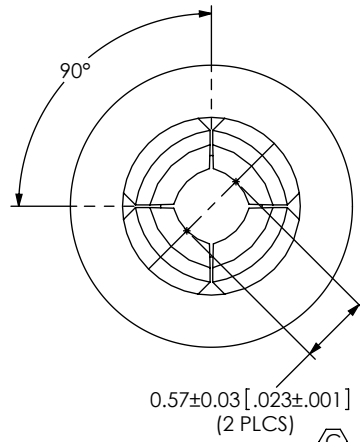
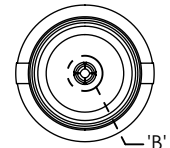
DETAIL 'A' SCALE 8:1



MBNC7-J-P-XX-ST-TH1

GENDER -J: JACK  
 TYPE -P: PCB  
 TERMINATION -TH1: THROUGH HOLE  
 ORIENTATION -ST: STRAIGHT

PLATING SPECIFICATION  
 -HN: HEAVY GOLD/NICKEL (SEE NOTES 7 & 8) (MBNC7-J-P-N-ST-TH1-BDY) (MBNC7-J-P-ST-TH1-INS) (MBNC7-J-P-H-ST-TH1-SKT)  
 -MN: MEDIUM GOLD/NICKEL (SEE NOTES 7 & 8) (MBNC7-J-P-N-ST-TH1-BDY) (MBNC7-J-P-ST-TH1-INS) (MBNC7-J-P-M-ST-TH1-SKT)



DETAIL 'B' SCALE 16:1

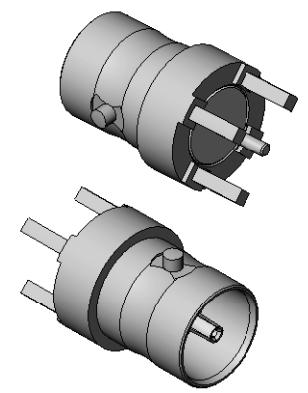


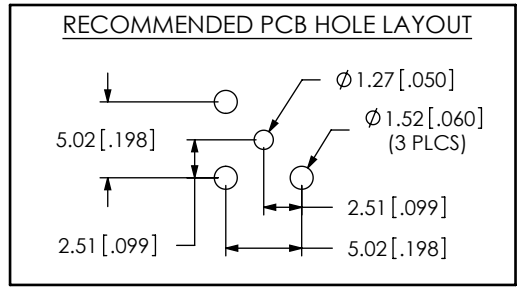
FIG.1 MBNC7-J-P-XX-ST-TH1 SHOWN

POSITION INSULATOR+0.10 [.004] OUTSIDE TO -0.10 [.004] INSIDE BODY

- NOTES:
- ⊕ REPRESENTS A CRITICAL DIMENSION.
  - PUSHOUT FORCE FOR CENTER CONTACT: 26.69 N [6.00 LB] MIN. FOR INSULATOR: 53.38 N [12.00 LB] MIN.
  - NOTE DELETED.
  - PRODUCT TO BE PACKAGED PER PACKAGING STANDARD CO-HD-WI-3040-M. USE SAMTEC TRAY TY-SMA001-1 AND TY-SMA001-2. QUANTITIES LESS THAN A FULL TRAY WILL NOT BE PACKAGED IN TRAYS.
  - RoHS COMPLIANT.
  - ALL PLATING MUST PASS SOLDERABILITY TEST PER MIL-STD-202G, METHOD 208H USING TYPE "R" FLUX.
  - COMPONENT PLATING DESIGNATIONS:  
 -H: 0.000030" MIN. GOLD OVER 0.000050" MIN. NICKEL.  
 -M 0.000010" MIN. GOLD OVER 0.000050" MIN. NICKEL.  
 -N: 0.000100" MIN. NICKEL.
  - ASSEMBLY PLATING DESIGNATIONS:  
 -HN: (CENTER CONTACT)-H (OUTER CONTACT) -N (REMAINING METAL PARTS) -N  
 -MN: (CENTER CONTACT)-M (OUTER CONTACT) -N (REMAINING METAL PARTS) -N

F:\DWG\MISC\MKTG\MBNC7-J-P-XX-ST-TH1-MKT.SLDDRW

**THIS PRODUCT MANUFACTURED WITH LEAD-FREE PROCESSING**



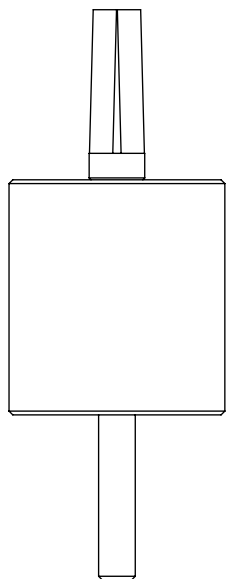
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS [INCHES]  
 TOLERANCES ARE:  
 DECIMALS ANGLES  
 .X: ±0.3 [.01] 2°  
 .XX: ±0.13 [.005]  
 .XXX: ±0.051 [.0020]

PROPRIETARY NOTE  
 THIS DOCUMENT CONTAINS INFORMATION CONFIDENTIAL AND PROPRIETARY TO SAMTEC, INC. AND SHALL NOT BE REPRODUCED OR TRANSFERRED TO OTHER DOCUMENTS OR DISCLOSED TO OTHERS OR USED FOR ANY PURPOSE OTHER THAN THAT WHICH IT WAS OBTAINED WITHOUT THE EXPRESSED WRITTEN CONSENT OF SAMTEC, INC.

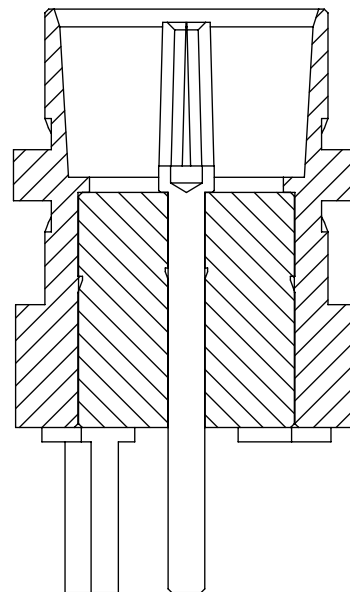
MATERIAL: DO NOT SCALE DRAWING SHEET SCALE: 2:1  
 BODY: BRASS  
 CONTACT: COPPER ALLOY  
 DIELECTRIC: PTFE

**samtec**  
 520 PARK EAST BLVD. NEW ALBANY, IN 47150  
 PHONE: 812-944-6733 FAX: 812-948-5047  
 e-Mail info@SAMTEC.com code 55322

DESCRIPTION:  
 TRUE 75 OHM MINI BNC STRAIGHT JACK FOR PCB  
 DWG. NO. MBNC7-J-P-XX-ST-TH1  
 BY: J. BROWNING 11/16/2009 SHEET 1 OF 2



IN-PROCESS 1  
INSERT PIN



IN-PROCESS 2  
INSERT INSULATOR

**CRITICAL DIMENSION INSPECTION INSTRUCTION TABLE**

ASSEMBLY OPERATION	START-UP INSPECTION INSPECT CODE A	IN-PROCESS INSPECTION INSPECT CODE B
INSERT PINS	C1	
INSERT INSULATORS	C2	

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520 PARK EAST BLVD., NEW ALBANY, IN 47150  
PHONE: 812-944-6733 FAX: 812-948-5047  
e-Mail info@SAMTEC.com code 55322

SHEET SCALE: 2:1

DESCRIPTION:  
TRUE 75 OHM MINI BNC STRAIGHT JACK FOR PCB

DWG. NO. MBNC7-J-P-XX-ST-TH1

BY: J. BROWNING 11/16/2009 SHEET 2 OF 2